TRF7960A NFC/HF RFID Transceiver IC

- Inductive Loop
- Antenna Tuning Section
- TX Impedance Matching/RX filter stage
- TX Out
- RX IN1
- RX IN2
- +2.7VDC to +5.5VDC
- 13.56MHz
- SPI or Parallel to MCU
- EN
- IRQ

TIDM-RFID-TRANSCEIVER Block Diagram (based on the TRF7960ATB)
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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